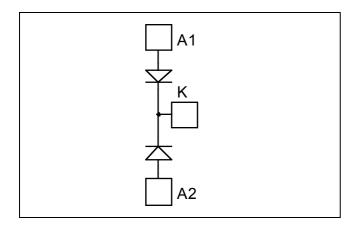


Dual Common Cathode diodes Power Module

$$V_{RRM} = 1700V$$

 $I_C = 400A$ @ $Tc = 55$ °C



Application

- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration



- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- **RoHS Compliant**

Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit	
V_R	Maximum DC reverse Voltage			1700	V	
V_{RRM}	Maximum Peak Repetitive Revers	titive Reverse Voltage				
т .	Maximum Average Forward	Destruction = 500/	$T_c = 25$ °C	480		
$I_{F(AV)}$	Current	Duty cycle = 50%	$T_c = 55$ °C	400	Α	
I _{F(RMS)}	RMS Forward Current			500	Α	
I_{FSM}	Non-Repetitive Forward Surge Current T _j		$T_j = 25$ °C	1500		

These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

	Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$V_{\rm F}$	V	Diode Forward Voltage	$I_F = 400A$	$T_i = 25^{\circ}C$		2.2	2.5	V
	v _F			$T_{i} = 125^{\circ}C$		2.1		·
I_{RM}	Maximum Reverse Leakage Current	$V_R = 1700V$	$T_i = 25^{\circ}C$			750	4	
			$T_j = 125$ °C			1000	μΑ	

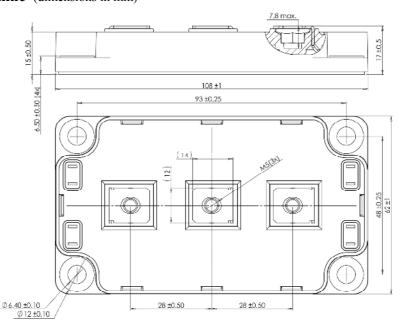
Dynamic Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t _{rr}	Reverse Recovery Time	$I_F = 400A$ $V_R = 900V$ $di/dt = 4000A/\mu s$	$T_j = 25$ °C		572		ns
			$T_j = 125$ °C		704		113
Q _{rr}	Reverse Recovery Charge		$T_j = 25$ °C		80		μС
			$T_{j} = 125^{\circ}C$		140		
I_{RRM}	Reverse Recovery Current		$T_j = 25^{\circ}C$		280		Α
			$T_j = 125$ °C		400		Λ

Thermal and package characteristics

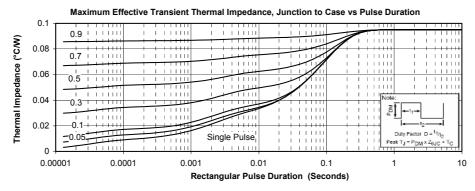
Symbol	Characteristic			Min	Тур	Max	Unit
R_{thJC}	Junction to Case Thermal Resistance					0.095	°C/W
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
T_{J}	Operating junction temperature range			-40		150	°C
T_{STG}	Storage Temperature Range Operating Case Temperature			-40		125	
$T_{\rm C}$				-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
Torque		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

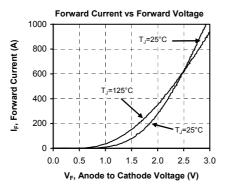
SP6 Package outline (dimensions in mm)

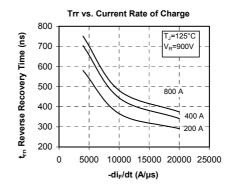


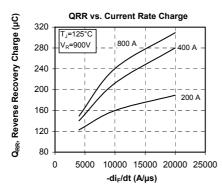


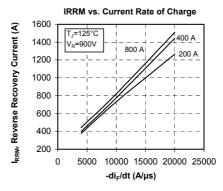
Typical Performance Curve

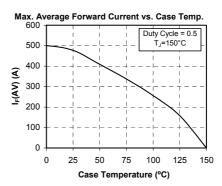












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